

N-Channel 20V(D-S) MOSFET

Product summary		
V_{DS}	20	V
$R_{DS(ON)}$ (at $V_{GS}=4.5V$) Typ.	190	m Ω
$R_{DS(ON)}$ (at $V_{GS}=2.5V$) Typ.	240	m Ω
I_D ($T_A=25^{\circ}C$)	0.7	A

Features

- Low Threshold Voltage
- ESD protection up to 2 kV
- Small package DFN1006-3L

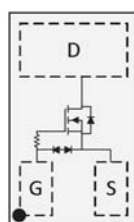
Applications

- Small Signal Switching
- Small Moto Driver

Pin Configuration



DFN1006-3L



Packing Information

Device	Package	Reel Size	Quantity(Min. Package)
ECAD2004T	DFN1006-3L	7"	10000pcs

Absolute Maximum Ratings (at $T_A=25^{\circ}C$ Unless Otherwise Noted)

Symbol	Parameter		Rating	Units
V _{DS}	Drain-Source Voltage		20	V
V _{GS}	Gate-Source Voltage		±8	V
I _D	Continuous Drain Current at V _{GS} =10V ^A	T _A =25°C	0.7	A
		T _A =70°C	0.52	A
I _{DM}	Pulse Drain Current Tested ^B		2.9	A
P _D	Power Dissipation ^A	T _A =25°C	0.28	W
T _J ,T _{STG}	Junciton and Storage Temperature Range		-55 to +150	°C

Thermal Characteristics

Symbol	Parameter	Typical	Units
$R_{\theta JA}$	Thermal Resistance-Junction to ambient A	446	$^{\circ}C/W$

Electrical Characteristics (at T_J =25°C Unless Otherwise Noted)

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
Static Parameters						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250uA	20	--	--	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =20V, V _{GS} =0V	--	--	1	uA
I _{GSS}	Gate-Body Leakage Current	V _{DS} =0V, V _{GS} =±8V	--	--	±10	uA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250uA	0.5	--	1.0	V
R _{DS(ON)}	Drain-Source On-State Resistance ^B	V _{GS} =4.5V, I _D =0.5A	--	190	280	mΩ
		V _{GS} =2.5V, I _D =0.5A	--	240	350	mΩ
		V _{GS} =1.8V, I _D =0.5A	--	310	450	mΩ
V _{SD}	Forward Voltage	I _{SD} =0.5A, V _{GS} =0V	--	--	1.3	V
Dynamic Parameters ^C						
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =10V f=1MHZ	--	46	--	pF
C _{oss}	Output Capacitance		--	9.8	--	pF
C _{rss}	Reverse Transfer Capacitance		--	7.2	--	pF
Q _g	Total Gate Charge	V _{DS} =10V, I _D =0.5A V _{GS} =4.5V	--	1.8	--	nC
Q _{gs}	Gate-Source Charge		--	0.15	--	nC
Q _{gd}	Gate-Drain Charge		--	0.25	--	nC
t _{D(on)}	Turn-on Delay Time	V _{DS} =10V I _D =0.5A, V _{GS} =4.5V, R _{GEN} =6Ω	--	34	--	ns
t _r	Turn-on Rise Time		--	97.3	--	ns
t _{D(off)}	Turn-off Delay Time		--	601	--	ns
t _f	Turn-off Fall Time		--	312	--	ns

A. The data tested by surface mounted on a 1 inch x 1 inch FR-4 board with 20Z copper.

B. Pulse Test: Pulse Width≤300us,Duty cycle ≤2%.

C. Guaranteed by design, not subject to production testing.

Typical Characteristics

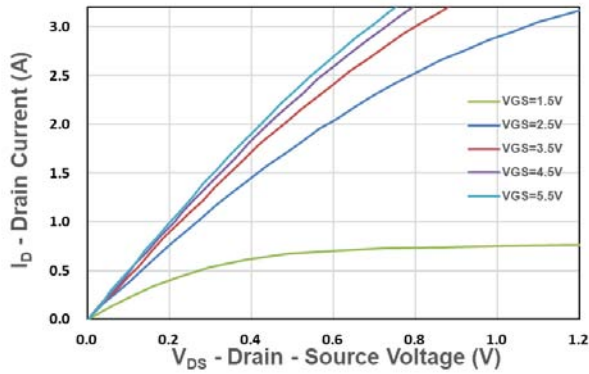


Figure 1. Output Characteristics

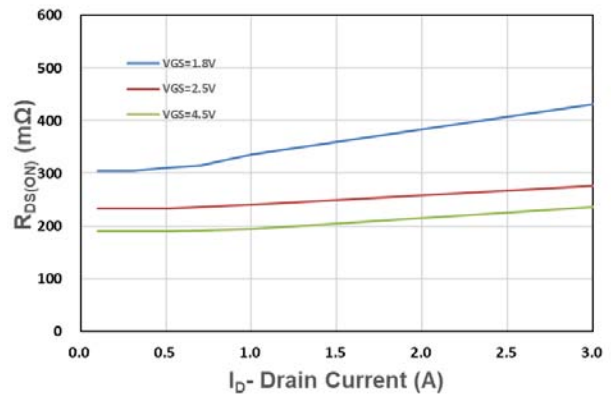


Figure 2. On-Resistance vs. I_D

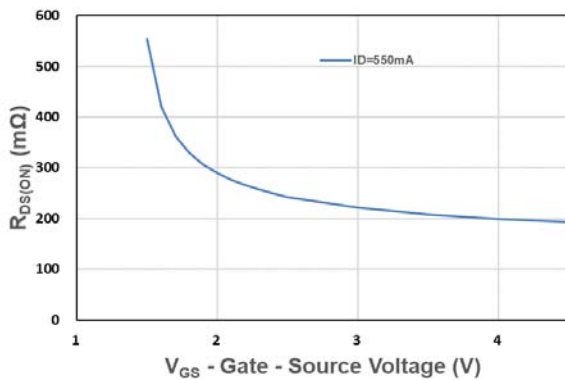


Figure 3. On-Resistance vs. V_{GS}

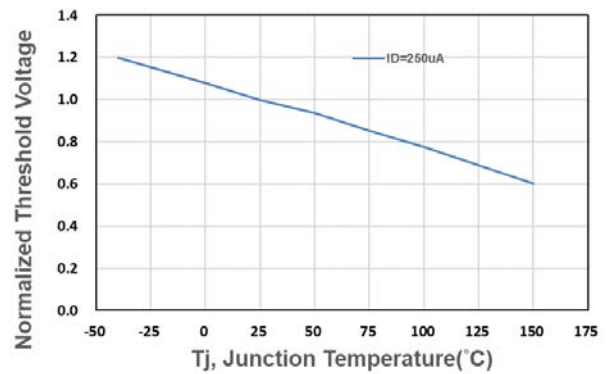


Figure 4. Gate Threshold Voltage

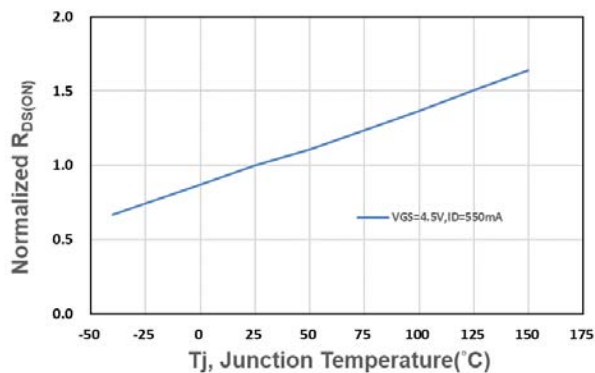


Figure 5. Drain-Source On Resistance

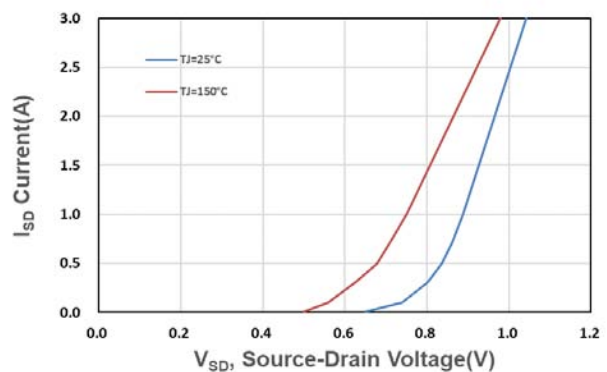


Figure 6. Source-Drain Diode Forward

Typical Characteristics

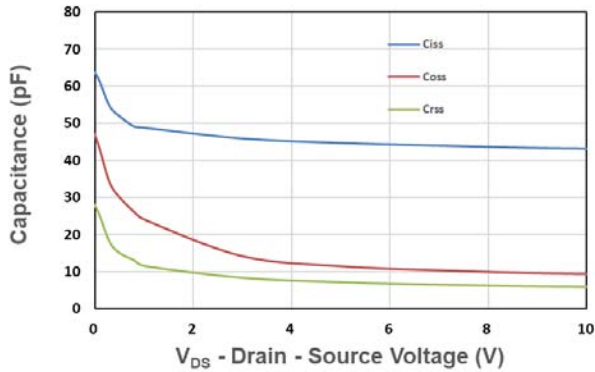


Figure 7. Capacitance

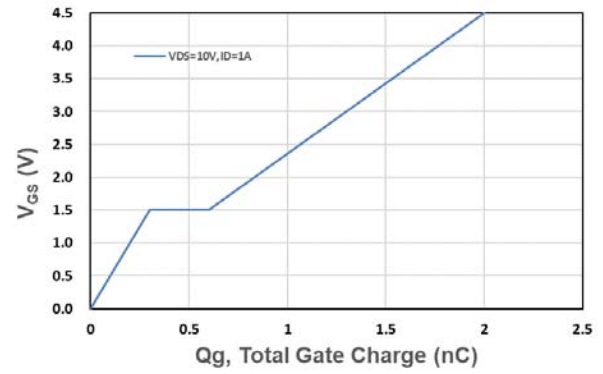


Figure 8. Gate Charge Characteristics

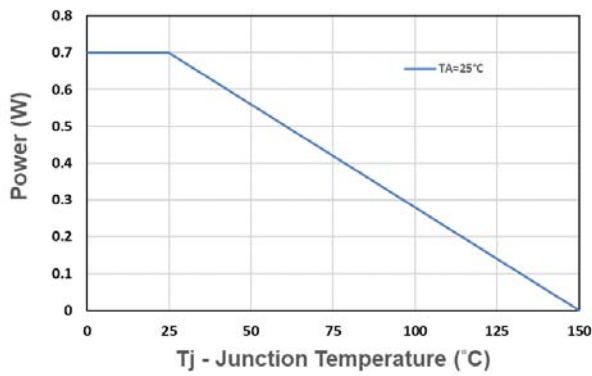


Figure 9. Power Dissipation

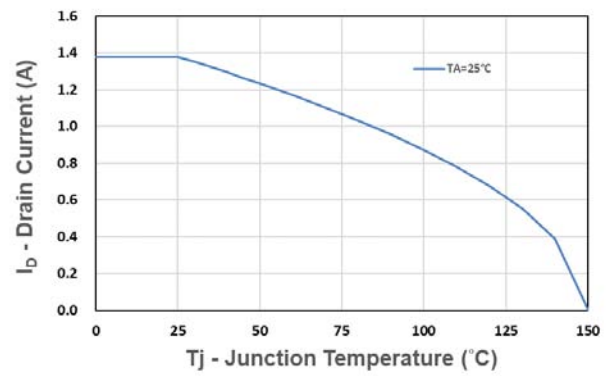


Figure 10. Drain Current

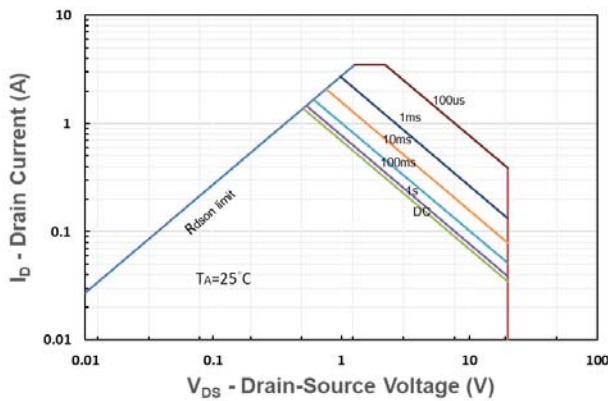


Figure 11. Safe Operating Area

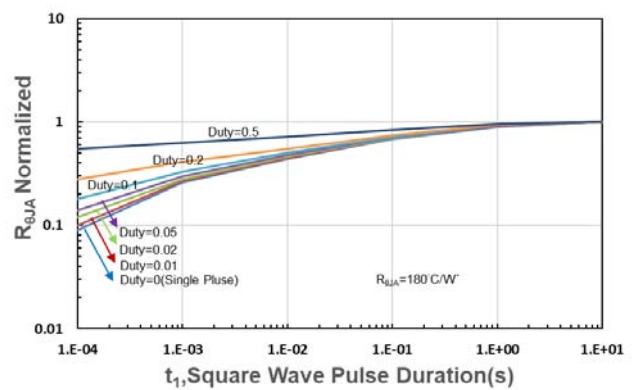
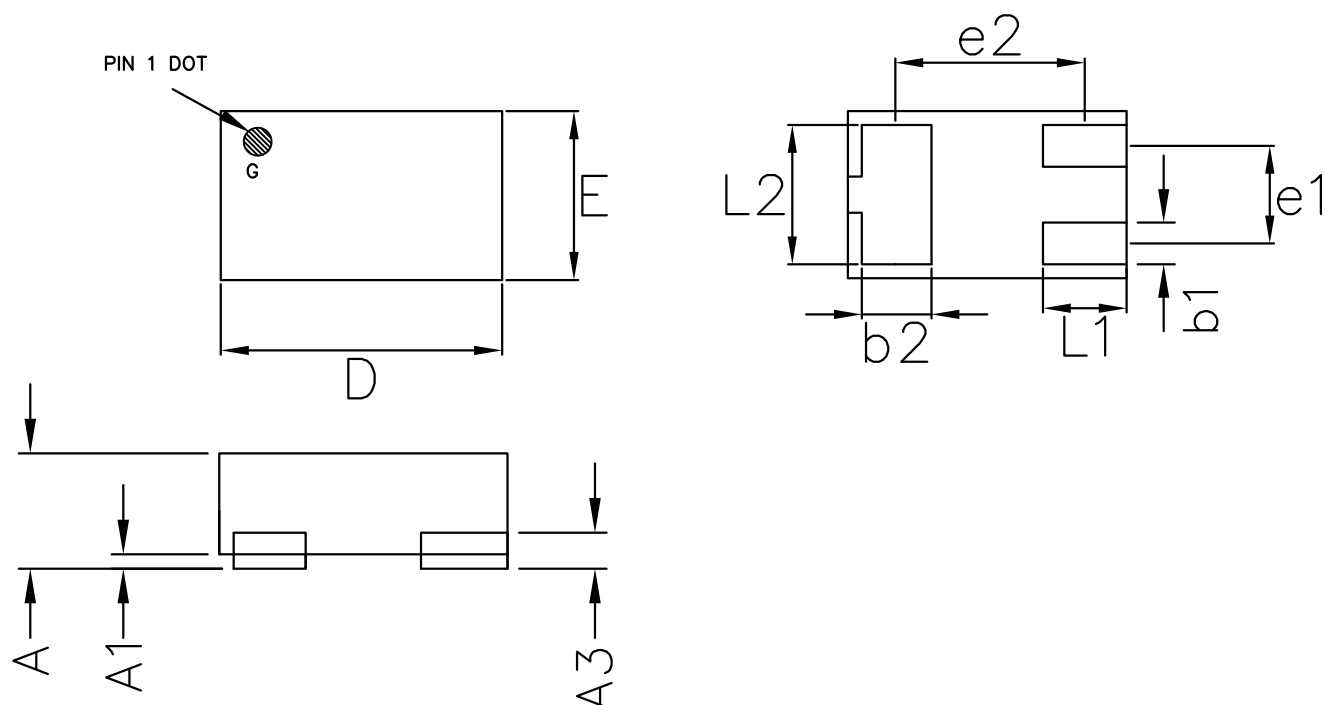


Figure 12. $R_{\theta JA}$ Transient Thermal Impedance

DFN1006-3L Package Information



COMMON DIMENSIONS(MM)			
PKG.	X1: EXTREME THIN		
REF.	MIN.	NOM.	MAX
A	0.30	—	0.40
A1	0.00	—	0.05
A3	0.125 REF.		
D	0.95	1.00	1.05
E	0.55	0.60	0.65
b1	0.10	0.15	0.20
b2	0.20	0.25	0.30
L1	0.20	0.30	0.40
L2	0.40	0.50	0.60
e1	0.35 BSC		
e2	0.675 BSC		